

Title (en)

ARRANGEMENT FOR DISSIPATING THERMAL ENERGY GENERATED BY HEAT SOURCE

Title (de)

VORRICHTUNG ZUR ABFUHR VON WÄRE, DIE VON EINER WÄRMEQUELLE ERZEUGT WIRD

Title (fr)

DISPOSITIF DISSIPATEUR DE L'ENERGIE THERMIQUE PRODUITE PAR UNE SOURCE THERMIQUE

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Application

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Abstract (en)

[origin: WO0103485A1] The invention relates to an arrangement for dissipating thermal energy generated by a heat source (1), which arrangement comprises a heat conductor element (2) for conducting thermal energy generated by the heat source (1) away from the heat source (1), the heat conductor element (2) having at least one micro heat pipe module (3) attached to it for distributing thermal energy generated by the heat source (1) in the heat conductor element (2). The heat source (1) is attached to an element (4) which is made of a heat conducting material and which is in thermal contact with the heat conductor element (2) and which is arranged to conduct thermal energy from the heat source (1) to the heat conductor element (2) by means of the heat conducting ability of said heat conducting material.

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